High Power LED Series Chip on Board

LCoo8B Gen.2



High efficacy COB LED package, well-suited for use in spotlight applications



Features & Benefits

- Chip on Board (COB) solution makes it easy to design in
- Simple assembly reduces manufacturing cost
- Low thermal resistance
- InGaN/GaN MQW LED with long time reliability
- Completed 9,000 hours of LM-80 Testing

Applications

- Spotlight / Downlight
- LED Retrofit Bulbs
- Outdoor Illumination







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1. Characteristics

a) Absolute Maximum Rating

ltem	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	Ta	-40 ~ +105	°C	-
Storage Temperature	T_{stg}	-40 ~ +120	°C	-
LED Junction Temperature	T _j	140	°C	-
Case Temperature	Tc	105	°C	*Note
Forward Current	l _F	430	mA	-
Power Dissipation	P_{D}	15.8	W	-
ESD (HBM)	-	±2	kV	-
ESD (MM)	-	±0.5	kV	-

b) Electro-optical Characteristics ($I_F = 240$ mA, $T_a = 25$ °C)

ltem	Unit	Rank	Min.	Тур.	Max.
Forward Voltage (V _F)	V	YH	33.5	36.5	39.5
		5	80	-	-
Color Rendering Index (R _a)	-	7	90	-	-
Thermal Resistance (junction to chip point)	°C/W		-	2.0	-
Beam Angle	0		-	115	-
Nominal Power	W			8.6	
Eye Protection		Risk 1	-		-

Notes:

- 1) The COB is tested in pulsed condition at rated test current (10 ms pulse width) and rated temperature $(T_j = T_c = T_a = 25 \text{ °C})$
- 2) Samsung maintains measurement tolerance of: forward voltage = ± 5 %, CRI = ± 1
- 3) Max Tc=105 Penta tisnfox EN/EC condition. Refer to the derating curve, '3. Typical Characteristics Graph'
- 4) designed within the range.



c) Luminous Flux Characteristics (I_F = 240 mA, T_a = 25 °C)

CRI (R _a)	Nominal	Flux	Flux	Sorting ¹⁾ @ 1	Sorting ¹⁾ @ T _c = 25 °C (lm)		@ T _c = 85 °C (lm)
Min.	CCT (K)	Rank	Bin	Min.	Max.	Min.	Max.
			K3	1041	1114	947	1014
		KG	K4	1114	1187	1014	1080
	2700		K5	1187	1260	1080	1147
	-	KH	K4	1114	1187	1014	1080
		КΠ	K5	1187	1260	1080	1147
			K3	1108	1185	1008	1078
		KG	K4	1185	1263	1078	1149
	3000		K5	1263	1340	1149	1219
	-	1/1.1	K4	1185	1263	1078	1149
		KH	K5	1263	1340	1149	1219
			K3	1141	1221	1038	1111
		KG	K4	1221	1300	1111	1183
	3500		K5	1300	1380	1183	1256
80			K4	1221	1300	1111	1183
		KH	K5	1300	1380	1183	1256
	4000		K3	1174	1256	1068	1143
		KG	K4	1256	1338	1143	1218
			K5	1338	1420	1218	1293
		KH	K4	1256	1338	1143	1218
			K5	1338	1420	1218	1293
			K3	1185	1268	1078	1154
	5000	KG	K4	1268	1351	1154	1229
		KH	K4	1268	1351	1154	1229
			K3	1185	1268	1078	1154
	5700	KG	K4	1268	1351	1154	1229
		KH	K4	1268	1351	1154	1229
	05		F3	933	1008	849	917
	2700	FH	F4	1008	1083	917	985
	0000	- /-	F3	952	1029	867	936
00	3000	FH	F4	1029	1105	936	1005
90	0.5		F3	981	1060	893	964
	3500	FH	F4	1060	1138	964	1036
	46		F3	1010	1090	919	992
	4000	FH	F4	1090	1171	992	1066

Notes:

- 1) The COB is tested in pulsed condition at rated test current (10 ms pulse width) and rated temperature ($T_j = T_c = T_a = 25$ °C)
- 2) Calculated flux values are for reference only
- 3) Samsung maintains measurement tolerance of: Iuminous flux = ± 7 %, CRI = ± 1



2. Product Code Information

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	Р	н	C	W	1	н	D	N	9	4	5	Υ	н	R	т	K	F

Digit	PKG Information	Code				Specific	ation
1 2 3	Samsung Package High Power	SPH					
4 5	Color	ww	Warm White	(T/U	/V/W Ran	ks)	
4 5	Coloi	CW	Cool White	(Q/R	Ranks)		
6	Product Version	1					
7 8	Form Factor	HD	СОВ				
9	Lens Type	N	No lens				
10	Internal Code	9	LC008				
11	Chip Type	4					
12	CRI & Sorting Temperature	5	Min. 80	25 °C			
12	CKI & Softling Temperature	7	Min. 90				
13 14	Forward Voltage (V)	YH	33.5~39.5				
		W	2700 K		WA,WB	(MacAdam Ellipse)	
		V	3000 K		VA, VB	(MacAdam Ellipse)	
15	CCT (K)	U	3500 K	Bin	UA, UB	(MacAdam Ellipse)	
13	COT (K)	Т	4000 K	Code:	TA, TB	(MacAdam Ellipse)	
		R	5000 K		RA	(MacAdam Ellipse)	RW, RX, RY, RZ (ANSI bin)
		Q	5700 K				QW, QX, QY, QZ (ANSI bin)
		2	MacAdam 2	2-step			
16	MacAdam / ANSI	3	MacAdam 3	8-step			
		Т	ANSI bin				
		KG			K3, K4	(80 CRI)	
17 18	Luminous Flux	KH		Bin Code:	K4, K5	(80 CRI)	
		FH			F3, F4	(90 CRI)	



a) Binning Structure (I_F = 240 mA, T_a = 25 °C)

CRI (R _a) Min.	Nominal CCT (K)	Product Code	V _F Rank	Color Rank	Chrom. Bin	Flux Rank	Flux Bin	Flux Range (Φ _v , lm)			
							K3	1041 ~ 1114			
		SPHWW1HDN945YHW2KG	YH	W2	WB	KG	K4	1114 ~ 1187			
							K5	1187 ~ 1260			
	-						K3	1041 ~ 1114			
	2700	SPHWW1HDN945YHW3KG	YH	W3	WA, WB	KG	K4	1114 ~ 1187			
	2700						K5	1187 ~ 1260			
		CDL IMMALIDNIO 4EVI IMMOVI I	VII	W/0	WD	IZI I	K4	1114 ~ 1187			
		SPHWW1HDN945YHW2KH	YH	W2	WB	KH	K5	1187 ~ 1260			
	.	ODLINANALI DNIO 45VI NAVOKLI	V/11	W/O	14/4 14/D	1711	K4	1114 ~ 1187			
		SPHWW1HDN945YHW3KH	YH	W3	WA, WB	KH	K5	1187 ~ 1260			
							K3	1108 ~ 1185			
		SPHWW1HDN945YHV2KG	YH	V2	VB	KG	K4	1185 ~ 1263			
							K5	1263 ~ 1340			
							K3	1108 ~ 1185			
	3000	SPHWW1HDN945YHV3KG	YH	V3	VA, VB	KG	K4	1185 ~ 1263			
80							K5	1263 ~ 1340			
		-			-		>41				K4
		SPHWW1HDN945YHV2KH	YH	V2	VB	KH	K5	1263 ~ 1340			
	-						K4	1185 ~ 1263			
		SPHWW1HDN945YHV3KH	YH	V3	VA, VB	KH	K5	1263 ~ 1340			
							K3	1141 ~ 1221			
		SPHWW1HDN945YHU2KG	YH	U2	UB	KG	K4	1221 ~ 1300			
							K5	1300 ~ 1380			
							K3	1141 ~ 1221			
		SPHWW1HDN945YHU3KG	YH	U3	UA, UB	KG	K4	1221 ~ 1300			
	3500						K5	1300 ~ 1380			
							K4	1221 ~ 1300			
		SPHWW1HDN945YHU2KH	YH	U2	UB	KH	K5	1300 ~ 1380			
							K4	1221 ~ 1300			
		SPHWW1HDN945YHU3KH	YH	U3	UA, UB	KH	K5	1300 ~ 1380			



a) Binning Structure ($I_F = 240 \text{ mA}, T_a = 25 \text{ }^{\circ}\text{C}$)

CRI (R _a) Min.	Nominal CCT (K)	Product Code	V _F Rank	Color Rank	Chrom. Bin	Flux Rank	Flux Bin	Flux Range (Φ _v , lm)			
							K3	1174 ~ 1256			
		SPHWW1HDN945YHT2KG	YH	T2	ТВ	KG	K4	1256 ~ 1338			
						•	K5	1338 ~ 1420			
				•••••			K3	1174 ~ 1256			
	4000	SPHWW1HDN945YHT3KG	YH	Т3	TA, TB	KG	K4	1256 ~ 1338			
	4000					•	K5	1338 ~ 1420			
	••	SPHWW1HDN945YHT2KH	YH	T2	ТВ		K4	1256 ~ 1338			
		SPHWW INDIN945 IN IZKH	ĬП	12	IB	KH	K5	1338 ~ 1420			
		SPHWW1HDN945YHT3KH	V/11	T0	TA TD	1711	K4	1256 ~ 1338			
80		SPHWW1HDN945YH13KH	YH	Т3	TA, TB	KH	K5	1338 ~ 1420			
		SPHCW1HDN945YHR3KG	YH	R3	DΛ	KG	K3	1185 ~ 1268			
		SPRCW INDIVISAS I RISKG	ĬП	KS	RA	KG .	K4	1268 ~ 1351			
	5000		VI.I	RT	RW, RX,	KG	K3	1185 ~ 1268			
		5000	5000	5000	SPHCW1HDN945YHRTKG	YH	KI	RY, RZ	KG	K4	1268 ~ 1351
		SPHCW1HDN945YHR3KH	ΥH	R3	RA	KH	K4	1268 ~ 1351			
	-	SPHCW1HDN945YHRTKH	YH	RT	RW, RX, RY, RZ	KH	K4	1268 ~ 1351			
		CDI IOWALIDNIGAEVI IOTICO	VII	OT	QW, QX,	V.C	K3	1185 ~ 1268			
	5700	SPHCW1HDN945YHQTKG	YH	QT	QY, QZ	KG	K4	1268 ~ 1351			
	-	SPHCW1HDN945YHQTKH	YH	QT	QW, QX, QY, QZ	KH	K4	1268 ~ 1351			

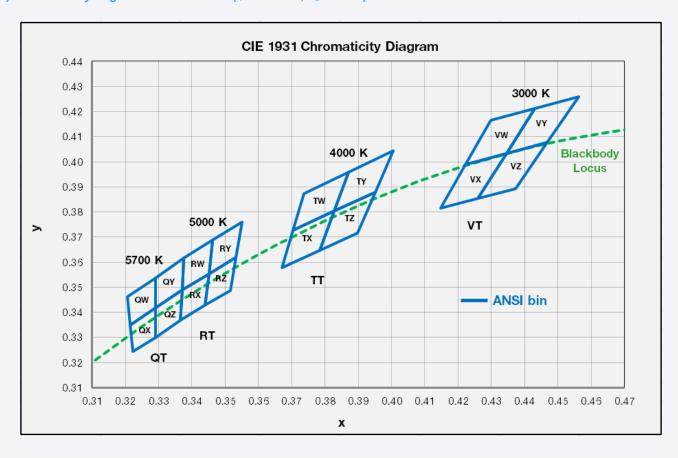


a) Binning Structure (I_F = 240 mA, T_a = 25 °C)

CRI (R₃) Min.	Nominal CCT (K)	Product Code	V _F Rank	Color Rank	Chrom. Bin	Flux Rank	Flux Bin	Flux Range (Φ _v , lm)	
		SPHWW1HDN947YHW2FH	YH	W2	WB	FH	F3	933 ~ 1008	
	2700	SPRVVVV INDN947 YNVV 2FR	ĬП	VVZ	VVD	гп -	F4	1008 ~ 1083	
	2700	SPHWW1HDN947YHW3FH	YH	W3	WA, WB	FH	F3	933 ~ 1008	
		SPRVVVV INDN947 YRVV3FR	ĬП	VV3	VVA, VVB	гп	F4	1008 ~ 1083	
		SPHWW1HDN947YHV2FH	YH	V2	VB	FH	F3	952 ~ 1029	
	3000	3F110000 111D10947 1110 2111	111	V Z	V D	111	F4	1029 ~ 1105	
		SPHWW1HDN947YHV3FH	ΥH	V3	VA, VB	FH ·	F3	952 ~ 1029	
90		3F110000 111D10947 11103111	111	V3	VA, VB	111	F4	1029 ~ 1105	
90		SPHWW1HDN947YHU2FH	YH	U2	LID	FH	F3	981 ~ 1060	
	3500	SPHWW1HDN947YHU2FH	111	02	UB	111	F4	1060 ~ 1138	
	3500	3500	SPHWW1HDN947YHU3FH	YH	U3	UA, UB	FH	F3	981 ~ 1060
		SPRWWINDIN94/TROSER	IП	03	UA, UB	гп	F4	1060 ~ 1138	
		SDUMMALIDNIGATVUTOEU	YH	T2	TD	FH	F3	1010 ~ 1090	
	4000	SPHWW1HDN947YHT2FH	IΠ	12	ТВ	ГП	F4	1090 ~ 1171	
	4000	SPHWW1HDN947YHT3FH	YH	T0 T4 TD	TA TD 511	F3	1010 ~ 1090		
		3FHWWW1HDN94/1H13FH	ĭΠ	Т3	TA, TB	FH	F4	1090 ~ 1171	



b) Chromaticity Region & Coordinates ($I_F = 240 \text{ mA}, T_a = 25 \text{ }^{\circ}\text{C}$)

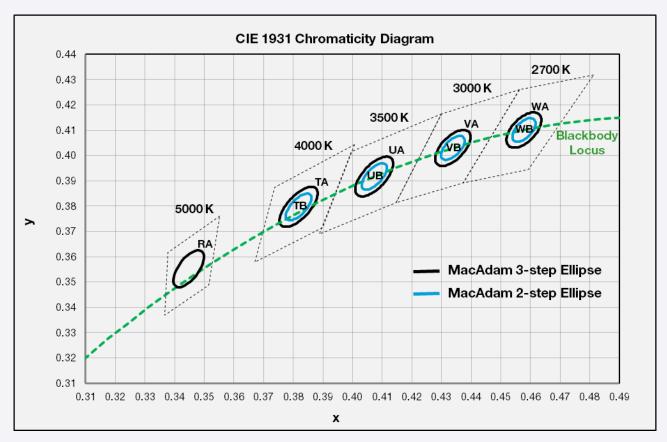


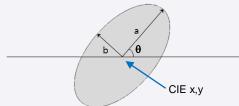
Region	CIE x	CIE y	Region	CIE x	CIE y
		V rank	(3000 K)		
	0.4223	0.399		0.4345	0.4033
VW	0.4345	0.4033	VY	0.4468	0.4077
VVV	0.4431	0.4213	VY	0.4562	0.4260
	0.4299	0.4165		0.4431	0.4213
	0.4223	0.399		0.4260	0.3854
VX	0.4147	0.3814	VZ	0.4373	0.3893
VA	0.4260	0.3854	۷Z	0.4468	0.4077
	0.4345	0.4033		0.4345	0.4033
		R rank	(5000 K)		
	0.3376	0.3616		0.3463	0.3687
RW	0.3463	0.3687	RY	0.3551	0.3760
KVV	0.3451	0.3554	KY	0.3533	0.3620
	0.3371	0.3490		0.3451	0.3554
	0.3371	0.3490		0.3451	0.3554
RX	0.3451	0.3554	R7	0.3533	0.3620
KX	0.3440	0.3428	KZ.	0.3515	0.3487
	0.3366	0.3369		0.3440	0.3428

Region	CIE x	CIE y	Region	CIE x	CIE y
		T rank	(4000 K)		
	0.3736	0.3874		0.3871	0.3959
TW	0.3871	0.3959	TY	0.4006	0.4044
IVV	0.3828	0.3803	11	0.3952	0.388
	0.3703	0.3726		0.3828	0.3803
	0.3703	0.3726		0.3828	0.3803
TX	0.3828 0.3803 TZ	0.3952	0.388		
1.7	0.3784	0.3647	12	0.3898	0.3716
	0.367	0.3578		0.3784	0.3647
		Q rank	(5700 K)		
	0.3207	0.3462		0.3290	0.3538
OW	0.3290	0.3538	ΟY	0.3376	0.3616
QVV	0.3290	0.3417	Qĭ	0.3371	0.3490
	0.3215	0.3350		0.3290	0.3417
	0.3215	0.3350	0.7	0.3290	0.3417
OX	0.3290	0.3417		0.3371	0.3490
QA	0.3290	0.3300	QZ	0.3366	0.3369
	0.3222	0.3243		0.3290	0.3300



b) Chromaticity Region & Coordinates ($I_F = 240 \text{ mA}$, $T_a = 25 \, ^{\circ}\text{C}$)





	MacAdam Ellipse (WA, WB)										
Step	CIE x	CIE y									
2-step	0.4578	0.4101	53.70	0.0054	0.0028						
3-step	0.4578	0.4101	53.70	0.0081	0.0042						

MacAdam Ellipse (UA, UB)							
Step CIE x CIE y θ a b							
2-step	0.4073	0.3917	54.00	0.0062	0.0028		
3-step	0.4073	0.3917	54.00	0.0093	0.0041		

MacAdam Ellipse (RA)								
Step CIE x CIE y θ a b								
3-step 0.3447 0.3553 59.62 0.0082 0.0035								

MacAdam Ellipse (VA, VB)								
Step	Step CIE x CIE y θ a b							
2-step	0.4338	0.403	53.22	0.0056	0.0027			
3-step	0.4338	53.22	0.0083	0.0041				

MacAdam Ellipse (TA, TB)							
Step CIE x CIE y θ a b							
2-step	0.3818	0.3797	53.72	0.0063	0.0027		
3-step	0.3818	0.3797	53.72	0.0094	0.0040		

Note:

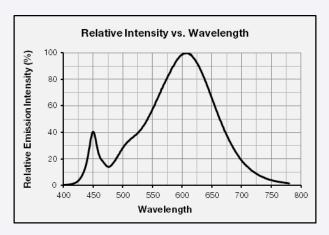
Samsung maintains measurement tolerance of: Cx, $Cy = \pm 0.005$



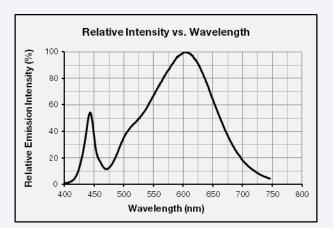
3. Typical Characteristics Graphs

a) Spectrum Distribution ($I_F = 240 \text{ mA}, T_a = 25 \text{ }^{\circ}\text{C}$)

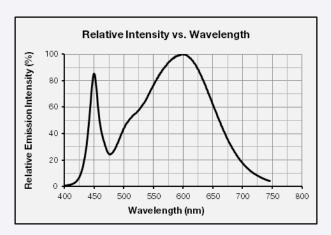
CCT: 2700 K



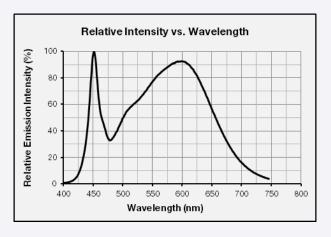
CCT: 3000 K



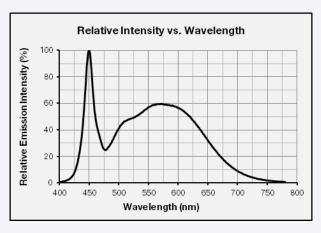
CCT: 3500 K



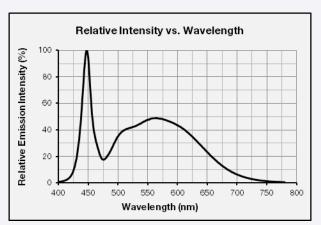
CCT: 4000 K



CCT: 5000 K

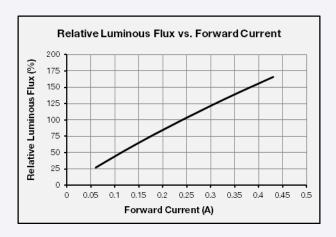


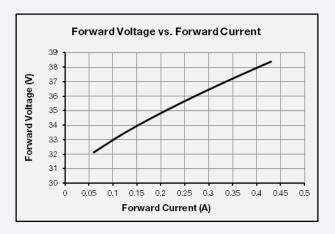
CCT: 5700 K



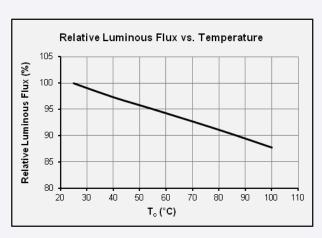


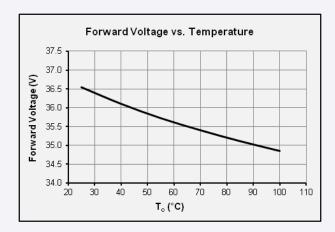
b) Forward Current Characteristics (T_a = 25 °C)



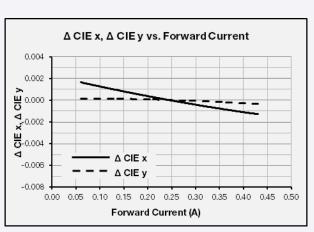


c) Temperature Characteristics (I_F = 240 mA)

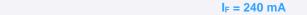


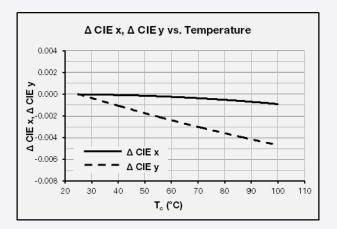


d) Color Shift Characteristics



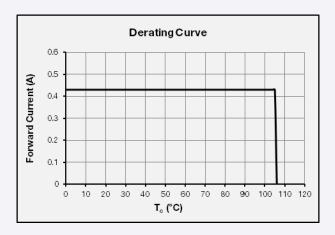
T_a = 25 °C



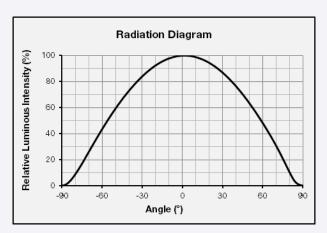




e) Derating Curve

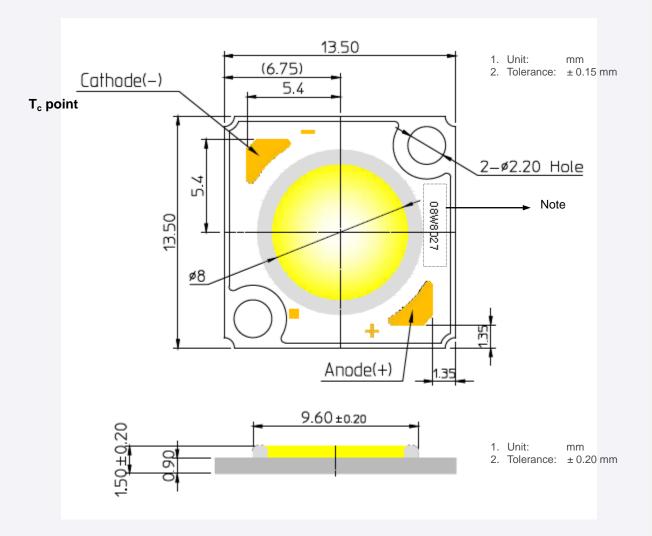


f) Beam Angle Characteristics ($I_F = 240$ mA, $T_a = 25$ °C)





4. Outline Drawing & Dimension



ltem	Dimension	Tolerance	Unit
Length	13.50	±0.15	mm
Width	13.50	±0.15	mm
Height	1.50	±0.20	mm
Light Emitting Surface (LES) Diameter	8	±0.15	mm
Screw Hole Size	2.2	±0.15	mm

Note: Denoted product information above is only an example

(08W8027:8.6W, CRI80+, 2700K)



5. Reliability Test Items & Conditions

a) Test Items

Test Item	Test Condition	Test Hour / Cycle
Room Temperature Life Test	25 °C, I _F = max	1000 h
High Temperature Humidity Life Test	60 °C, 90 % RH, DC Derating, I _F = max	1000 h
High Temperature Life Test	105 °C, DC Derating, I _F = max	1000 h
Low Temperature Life Test	-40 °C, DC 430 mA	1000 h
High Temperature Storage	120 °C	1000 h
Low Temperature Storage	-40 °C	1000 h
Thermal Shock	-45 °C / 15 min ↔ 125 °C / 15 min temperature change in 5 min	200 cycles
Temperature Cycle On/Off Test	-40 °C / 85 °C each 20 min, 100 min transfer power on/off each 5 min, DC 240 mA	100 cycles
ESD (HBM)	R ₁ : 10 MΩ R ₂ : 1.5 kΩ C: 100 pF V: ±2 kV	5 times
ESD (MM)	R_{1} : $10~M\Omega$ R_{2} : $0~k\Omega$ C : $200~pF$ V : $\pm 0.5~kV$	5 times
Vibration Test	20 ~ 80 Hz (displacement: 0.06 inch, max. 20 g) 80 ~ 2 kHz (max. 20 g) min. frequency ↔ max. frequency 4 min transfer	4 times
Mechanical Shock Test	1500 g, 0.5 ms each of the 6 surfaces (3 axis x 2 sides)	5 times
Salt Spray Test	35 ℃, 5 % salt water 8 h spray, 16 h dwell	2 cycles

b) Criteria for Judging the Damage

ltom	Cumbal	Test Condition	Lin	Limit		
Item	Symbol	(T _c = 25 °C)	Min.	Max.		
Forward Voltage	V_{F}	$I_F = 240 \text{ mA}$	L.S.L. * 0.9	U.S.L. * 1.1		
Luminous Flux	Φ_{v}	I _F = 240 mA	L.S.L * 0.7	U.S.L * 1.3		

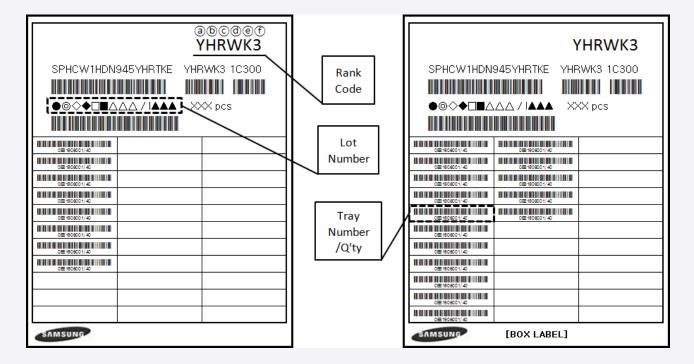


6. Label Structure

a) Label Structure

Aluminum Bag & Inner Box

Outer Box



Note: Denoted rank code and product code above is only an example (see description on page 5)

Rank Code:

(a) (refer to page 6-7)

©d: Chromaticity bin (refer to page 8-9)

(e)f): Luminous Flux bin (refer to page 6-7)



b) Lot Number

The lot number is composed of the following characters:

 $\bigcirc\bigcirc\diamondsuit\diamondsuit\Box$ $\bigcirc\triangle\triangle$ / 1 \triangle \triangle / xxx PCS

• : Production site (S: Giheung, Korea, G: Tianjin, China)

○ : L (LED)

: Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)

• Year (Y: 2014, Z: 2015, A: 2016, ...)

☐ : Month (1~9, A, B, C)

■ : Day (1~9, A, B~V)

 $\triangle \triangle \triangle$: Product serial number (001 ~ 009)

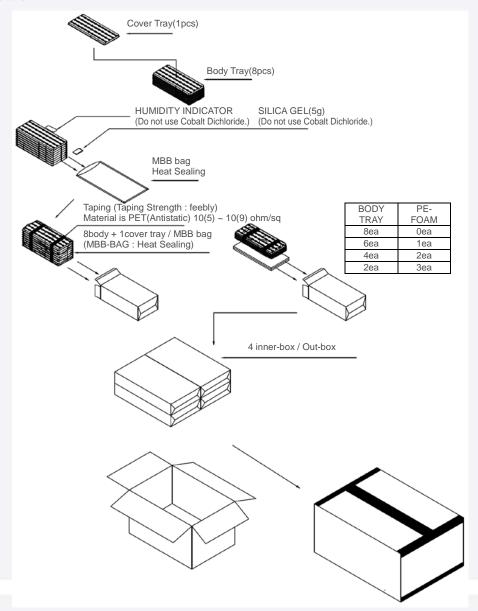
▲ ▲ ▲ : Tray number (001 ~ 999)



7. Packing Structure

Dacking material	Max. quantity	Dimension (mm)			
Packing material	Max. quantity in pcs of COB	Length	Width	Height	Tolerance
Tray	84	322.6	135.9	10.8	1.0
Aluminum Bag	672 (8 trays)	450	230	-	10
PE Foam Pad	-	280	130	10	2
Inner Box	672 (1 aluminum bag)	338	143	55	2
Outer Box	2,688 (4 inner boxes)	351	303	125	5
Pallet	150,528 (56 outer boxes)	1000	1000	130	10

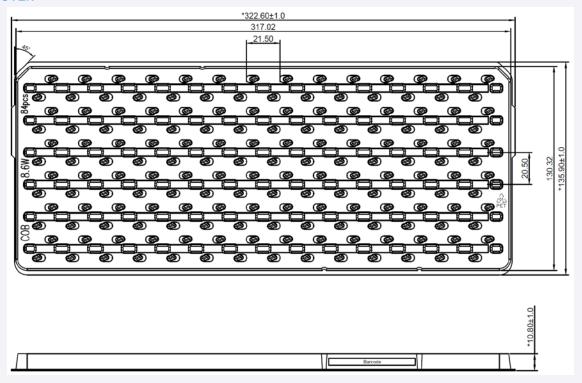
a) Packing Structure



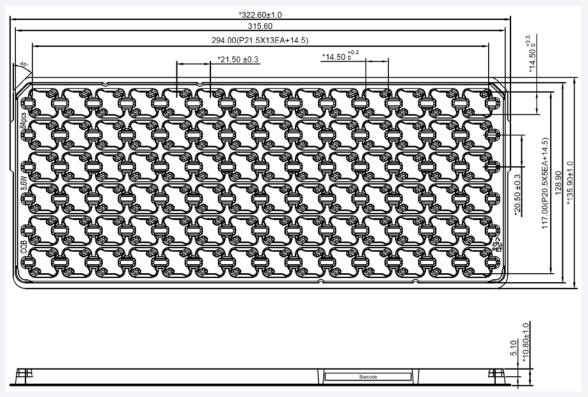


b) Tray

① COVER

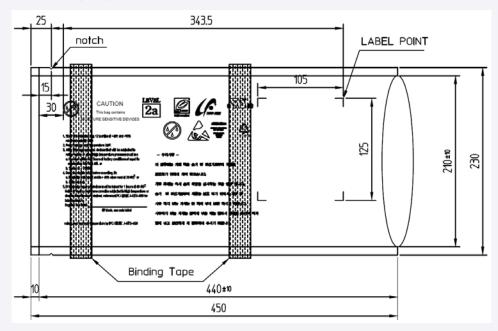


② BODY



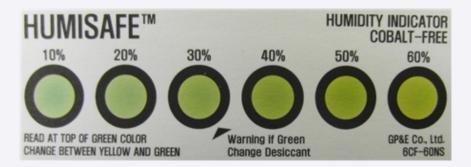


c) Aluminum Vinyl Packing Bag



d) Silica Gel & Humidity Indicator Card inside Aluminum Vinyl Packing Bag

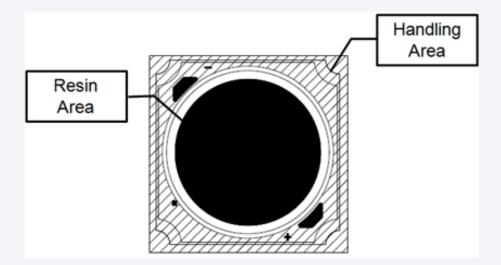






8. Precautions in Handling & Use

- This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA
 is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the
 device.
- 2) LEDs must be stored in a clean environment. If the LEDs are to be stored for three months or more after being shipped from Samsung, they should be packed with a nitrogen-filled container (shelf life of sealed bags is 12 months at temperature 0~40 °C, 0~90 % RH).
- 3) After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
 - a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 °C / 60 % RH, or
 - b. Stored at <10 % RH
- 4) Repack unused products with anti-moisture packing, fold to close any opening and then store in a dry place.
- 5) Devices require baking before mounting, if humidity card reading is >60 % at 23 ± 5 °C.
- 6) Devices must be baked for 1 hour at 60 ± 5 °C, if baking is required.
- 7) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- 8) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.
- 9) The resin area is very sensitive, please do not handle, press, touch, rub, clean, or pick by with tweezers on it. Instead, please pick at the handling area as indicated below.





Legal and additional information.

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Samsung Electronics Co., Ltd. inspires the world and shapes the future with transformative ideas and technologies, redefining the worlds of TVs, smartphones, wearable devices, tablets, cameras, digital appliances, printers, medical equipment, network systems and semiconductors. We are also leading in the Internet of Things space through, among others, our Digital Health and Smart Home initiatives. We employ 307,000 people across 84 countries. To discover more, please visit our official website at www.samsung.com and our official blog at global.samsungtomorrow.com.

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Samsung Electronics Co., Ltd. 95, Samsung 2-ro Giheung-gu Yongin-si, Gyeonggi-do, 446-711 KOREA

www.samsungled.com

